

To all our customers

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Renesas Technology Home Page: <http://www.renesas.com>

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

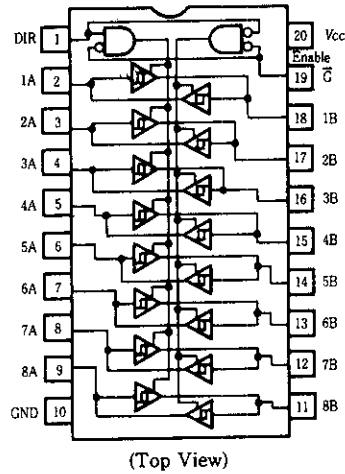
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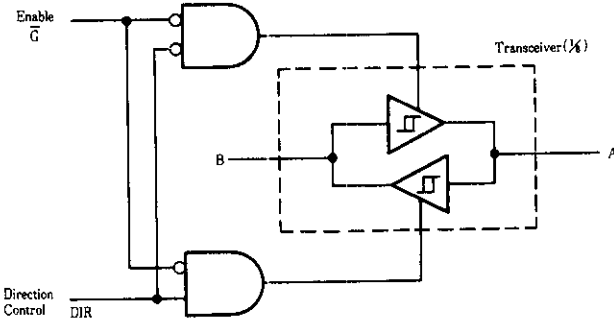
HD74LS641-1●Octal Bus Transceivers (non-inverted open-collector outputs)

This octal bus transceivers is designed for asynchronous two-way communication between data buses. The devices transmit data, from the A bus to the B bus or from the B bus to the A bus depending upon the level at the direction control (DIR) input. The enable input ($\bar{G}$) can be used to disable the device so that the buses are effectively isolated.

PIN ARRANGEMENT



BLOCK DIAGRAM



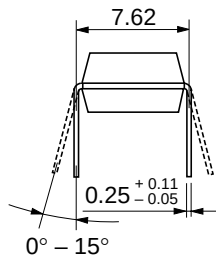
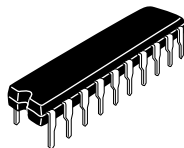
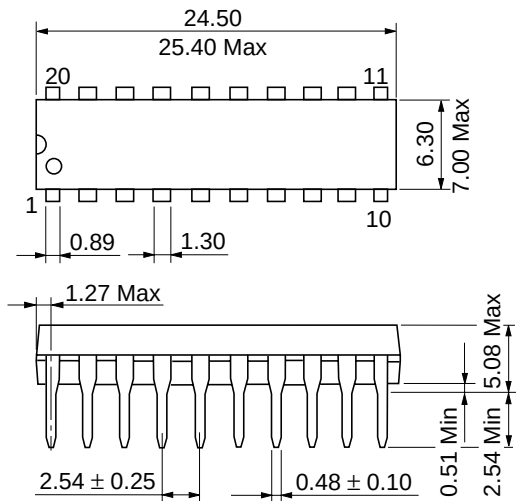
RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output voltage	V_{OH}	—	—	5.5	V
Output current	I_{OL}	—	—	48	mA
Operating temperature range	T_{opr}	-20	25	75	°C

FUNCTION TABLE

Enable	Direction Control	Operation
$\bar{G}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

Notes) H; high level, L; low level, X; irrelevant



Hitachi Code	DP-20N
JEDEC	—
EIAJ	Conforms
Weight (reference value)	1.26 g

Cautions

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